

24/09/03  
2003054145

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization  
International Bureau



\*162162\*

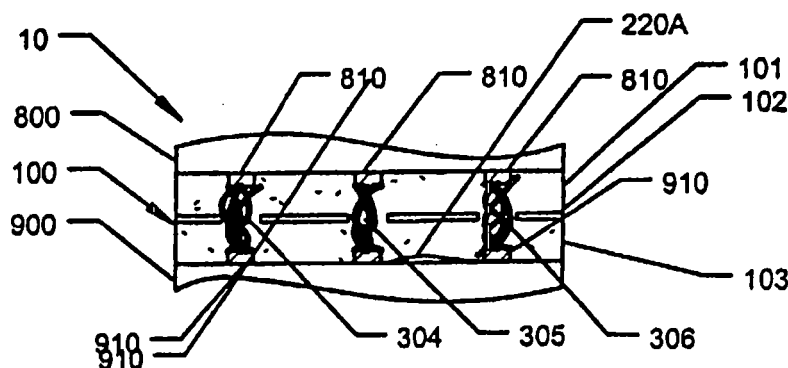
(43) International Publication Date  
3 October 2002 (03.10.2002)

PCT

(10) International Publication Number  
**WO 02/076735 A1**

- (51) International Patent Classification<sup>7</sup>: **B32B 31/04**, H01L 23/053 (74) Agents: **ZOETEWEEY, David** et al.; Rutan & Tucker, LLP, 611 Anton Blvd., 14th Floor, Costa Mesa, CA 92626 (US).
- (21) International Application Number: PCT/US02/07010 (81) Designated States (*national*): AE, AG, AL, AM, AT, AT (utility model), AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, CZ (utility model), DE, DE (utility model), DK, DK (utility model), DM, DZ, EC, EE, EE (utility model), ES, FI, FI (utility model), GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, OM, PH, PL, PT, RO, RU, SD, SE, SG, SI, SK, SK (utility model), SL, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VN, YU, ZA, ZM, ZW.
- (22) International Filing Date: 7 March 2002 (07.03.2002)
- (25) Filing Language: English
- (26) Publication Language: English
- (30) Priority Data: 09/818,324 26 March 2001 (26.03.2001) US
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- (84) Designated States (*regional*): ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).
- Published:
- with international search report
  - with amended claims
- For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.*

(54) Title: COMPLIANT PRE-FORM INTERCONNECT



(57) Abstract: An assembly (10) having a thermosetting layer (100) pierced by a plurality of conductors (300) is formed on a release sheet (200) and subsequently sandwiched between an IC and a PWB or other supporting surface and subsequently cured. The release sheet is removed either before or during curing of the thermosetting material. Removal prior to curing may be accomplished via peeling. Removal during curing may be by destruction of the layer by the curing process.

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